

T-Head Zhenwu M890

Zhenwu

2026

OVERVIEW

—	144 GB	—	—
FP32 TFLOPS	Memory HBM	Memory Bandwidth	TDP

PERFORMANCE METRICS

Precision	Peak (dense)	Bits	Type
FP64	—	—	Standard
FP32	—	32	Standard
TF32	—	—	Standard
BF16	—	16	Standard
FP16	—	16	Standard
FP8	—	8	Standard
FP6	—	—	Standard
FP4	—	4	Standard
INT8	—	8	Standard

MEMORY SPECIFICATIONS

Capacity	144 GB
Type	HBM
Bandwidth	—
Interface Width	—

POWER & EFFICIENCY

TDP	—
Max power	—
FP32 dense TFLOPS per W of TDP	—
FP16 dense TFLOPS per W of TDP	—
Per W of TDP figures divide dense peak by accelerator TDP. Board power only: excludes host CPUs, networking, cooling and facility overhead.	

HARDWARE DETAILS

Vendor: T-Head	Architecture: Zhenwu	Process Node: —
Form Factor: —	Launch Year: 2026	

INTERCONNECT

GPU-to-GPU: ICN Link	Bandwidth: 800 GB/s	Links: 8
direction and scope not stated by vendor		

PCIe: 5.0 x16